

Low-pressure plasma system V10-G

Efficient batch system for removal of photoresist

The system V10-G is suitable for industrial production as well as for R&D applications in the laboratory sector. The integrated professional PLC control serves as a storage for definable processes and parameters.

Areas of application

- Removal of photoresist layers (including SU-8) after dry processes such as RIE, electron beam etching, or ion beam etching, as well as after high-dose implant processes.
- Cleaning of wafers
- Improvement of the wettability of silicon wafers and other substrates prior to wet processing steps
- Application in MEMS and nanotechnology
- Removal of polymer residues after the Bosch process
- Removal of organic sacrificial layers
- Conditioning of bioactive compounds



System features

- Process chamber: quartz glass cylinder
- Pullout door
- Display of all process relevant parameters
- Archiving of all processes
- Remote maintenance (VPN)
- Ethernet interface

Options

- Vacuum pump (external)
- Ozone trap
- Up to two additional gas inlets
- Soft start and slow vent
- Faraday cage
- Process pressure control valve
- Oxygen concentrator
- Base frame



The low-pressure plasma system V10-G is equipped with a sliding door and a process chamber made of quartz glass and is also suitable for the cleaning of wafers.

Technical data

Dimensions of the system (W x D x H)	720 x 820 x 820 mm
Dimensions of the chamber (Ø x D)	215 x 260 mm
Plasma excitation frequency	Microwave (2.45 GHz)
Microwave power	50-600 W
Gas inlets with Mass-Flow-Controller	1 channel
Power supply	400 V, 50 / 60 Hz
Power input (without vacuum pump)	1.5 kVA
Vacuum gauge	Pirani
Weight	150 kg